



Product Change Notification

Change Notification #: 115736 - 00

Change Title: Intel® Omni-Path Edge Switch 100 Series 24 Port Managed Forward 2 PSU 100SWE24QF2,
Intel® Omni-Path Edge Switch 100 Series 48 Port Managed Forward 1 PSU 100SWE48QF1,
Intel® Omni-Path Edge Switch 100 Series 48 Port Managed Forward 2 PSU 100SWE48QF2,
Intel® Omni-Path Edge Switch 100 Series 24 Port Forward 1 PSU 100SWE24UF1,
Intel® Omni-Path Edge Switch 100 Series 24 Port Forward 2 PSU 100SWE24UF2,
Intel® Omni-Path Edge Switch 100 Series 48 Port Forward 1 PSU 100SWE48UF1,
Intel® Omni-Path Edge Switch 100 Series 48 Port Forward 2 PSU 100SWE48UF2,
Intel® Omni-Path Edge Switch Installation Kit 100 Series 100SWEIKIT1

PCN 115736-00, Manufacturing Site Change, Label Change

Date of Publication: August 17, 2017

Key Characteristics of the Change:
Manufacturing Site, Label

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	September 01, 2017
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The date of "First Availability of Post-Conversion Material" is the projected date that a customer may expect to receive the Post-Conversion Materials. This date is determined by the projected depletion of inventory at the time of the PCN publication. The depletion of inventory may be impacted by fluctuating supply and demand, therefore, although customers should be prepared to receive the Post-Converted Materials on this date, Intel will continue to ship and customers may continue to receive the pre-converted materials until the inventory has been depleted.

Description of Change to the Customer:

The manufacturing site of Omni-Path Edge Switches and Edge Switch Kits is being moved from Flextronics International USA in Milpitas, California to Flextronics Technologies Mexico in Guadalajara, Mexico.

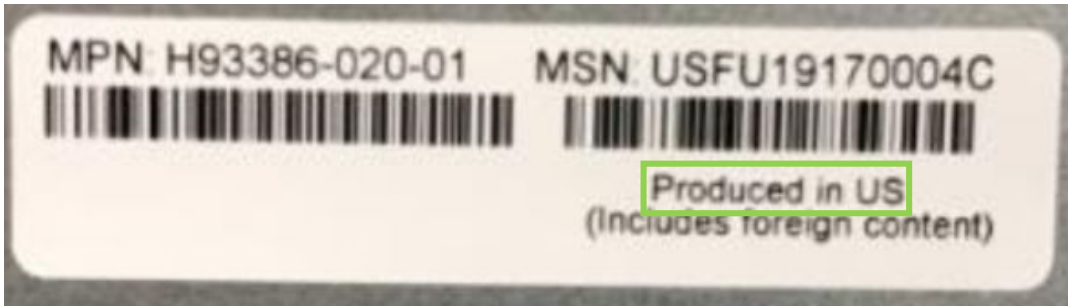
Affected Product Code	Affected Intel MM	Product Description
100SWE24QF2	945654	Intel® Omni-Path Edge Switch 100 Series 24 Port Managed Forward 2 PSU 100SWE24QF2
100SWE48QF1	945662	Intel® Omni-Path Edge Switch 100 Series 48 Port Managed Forward 1 PSU 100SWE48QF1
100SWE48QF2	948588	Intel® Omni-Path Edge Switch 100 Series 48 Port Managed Forward 2 PSU 100SWE48QF2
100SWE24UF1	945665	Intel® Omni-Path Edge Switch 100 Series 24 Port Forward 1 PSU 100SWE24UF1
100SWE24UF2	945655	Intel® Omni-Path Edge Switch 100 Series 24 Port Forward 2 PSU 100SWE24UF2
100SWE48UF1	945663	Intel® Omni-Path Edge Switch 100 Series 48 Port Forward 1 PSU 100SWE48UF1
100SWE48UF2	948678	Intel® Omni-Path Edge Switch 100 Series 48 Port Forward 2 PSU 100SWE48UF2
100SWEIKIT1	945820	Intel® Omni-Path Edge Switch Installation Kit 100 Series 100SWEIKIT1

Product Change Details:

The manufacturing site of Omni-Path Edge Switches and Edge Switch Kits is being moved from Flextronics International USA in Milpitas, California to Flextronics Technologies Mexico in Guadalajara, Mexico. This impacts the assembly and test location of all affected products.

To differentiate manufacturing site, Omni-Path products include several labels where this information is included. For example, on all Omni-Path Edge Switches the country of final manufacture is indicated on four labels on the device or packaging. Examples highlighting these labels for the 100SWE48QF2 produced both in the US and in Mexico can be seen below.

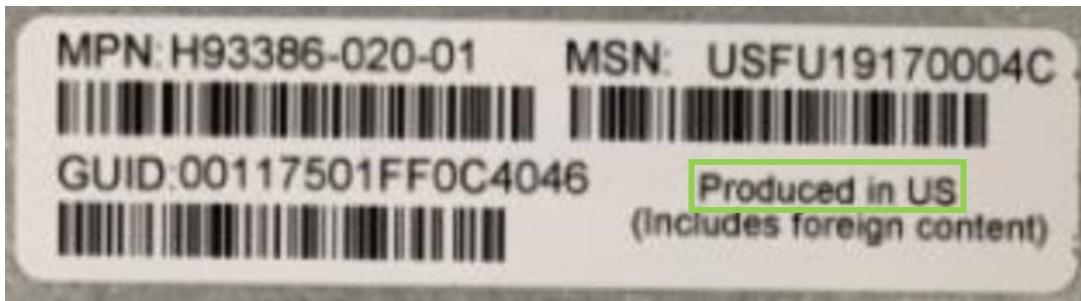
US-manufactured unit - internal switch label:



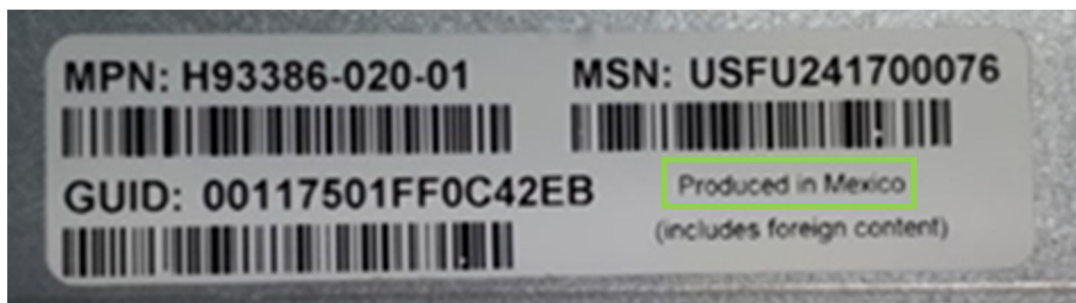
Mexico-manufactured unit - internal switch label:



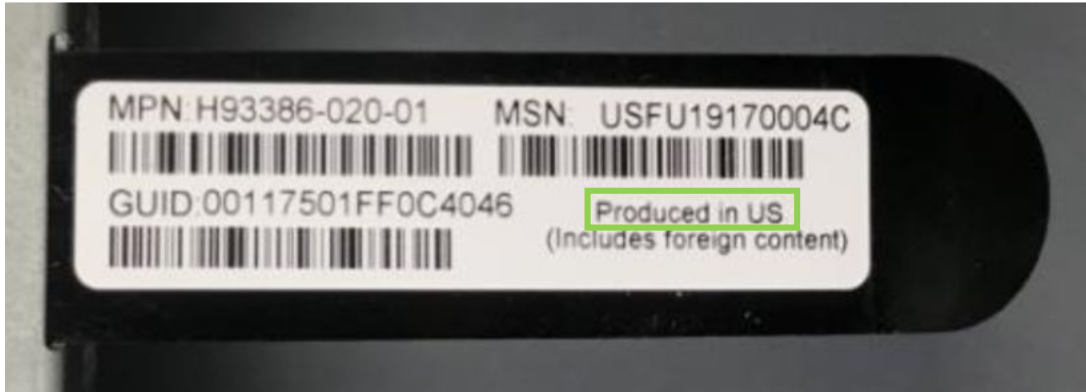
US-manufactured unit - product label (found on the bottom of the switch):



Mexico-manufactured unit - product label (found on the bottom of the switch):



US-manufactured unit - switch-tongue label:



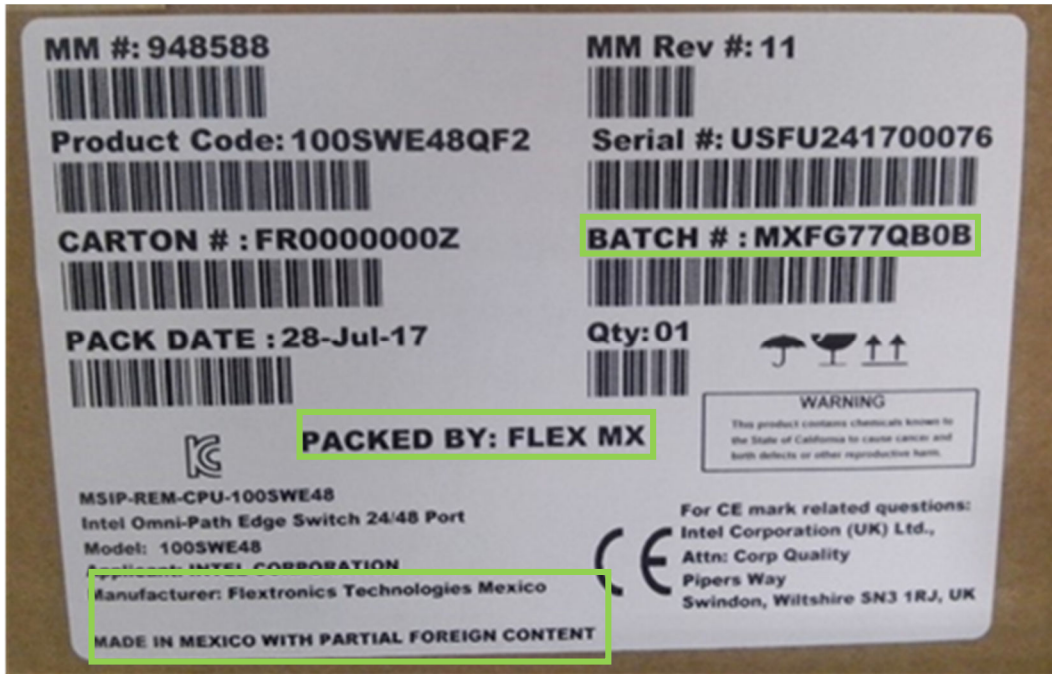
Mexico-manufactured unit - switch-tongue label:



US-manufactured unit - external packaging label:



Mexico-manufactured unit - external packaging label:



Summary table of the changes on the Omni-Patch Edge Switches shown above:

Text Changed	US-manufactured	Mexico-manufactured	Applies To
Location produced	Produced in US	Produced in Mexico	Internal switch label Product label Switch tongue label
Batch Code – First Two Digits	US	MX	External Packaging label
Packed By	Flex US	Flex MX	External Packaging label
KCC Registration Manufacturer	Flextronics International USA, Inc.	Flextronics Technologies Mexico	External Packaging label
Made In Location	Made in United States	Made in Mexico	External Packaging label

Customer Impact of Change and Recommended Action:

Intel is not recommending additional qualification of these changes by customers. There is no change to the switch Intel Material Master (MM) numbers or revisions. Please contact your local Intel Field Sales Representative if you have any questions about this change.

Milestone dates are estimates and subject to change based on business and operational conditions.

* Other names and brands may be claimed as the property of others.

Products Affected / Intel Ordering Codes:

Affected Product Code	Affected Intel MM	Product Description
100SWE24QF2	945654	Intel® Omni-Path Edge Switch 100 Series 24 Port Managed Forward 2 PSU 100SWE24QF2
100SWE48QF1	945662	Intel® Omni-Path Edge Switch 100 Series 48 Port Managed Forward 1 PSU 100SWE48QF1
100SWE48QF2	948588	Intel® Omni-Path Edge Switch 100 Series 48 Port Managed Forward 2 PSU 100SWE48QF2
100SWE24UF1	945665	Intel® Omni-Path Edge Switch 100 Series 24 Port Forward 1 PSU 100SWE24UF1
100SWE24UF2	945655	Intel® Omni-Path Edge Switch 100 Series 24 Port Forward 2 PSU 100SWE24UF2
100SWE48UF1	945663	Intel® Omni-Path Edge Switch 100 Series 48 Port Forward 1 PSU 100SWE48UF1
100SWE48UF2	948678	Intel® Omni-Path Edge Switch 100 Series 48 Port Forward 2 PSU 100SWE48UF2
100SWEIKIT1	945820	Intel® Omni-Path Edge Switch Installation Kit 100 Series 100SWEIKIT1

PCN Revision History:

Date of Revision:
August 17, 2017

Revision Number:
00

Reason:
Originally Published PCN



Product Change Notification

115736 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Americas Contact: asmo.pcn@intel.com

Asia Pacific/PRC Contact: apacgccb@intel.com

Europe Email: eccb@intel.com

Japan Email: jccb.ijkk@intel.com

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